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| FORM PTO-1449 (MODIFIED) LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS INFORMATION DISCLOSURE STATEMENT | ATTORNEY DOCKET NO. | SERIAL NO. |
| | SP03-091 | |
| | APPLICANT Paul S. Danielson et al. | |
| | FILING DATE | GROUP: TBA |

| REFERENCE DESIGNATION | | | | U.S. PATENT DOCUMENTS | | | |
|-----------------------|----|-----------------|----------|--------------------------|-------|-----------|------------------------|
| Examiner Initial | | Document Number | Date | Name | Class | Sub-Class | Filing Date if Approp. |
| <i>my</i> | AA | 4,544,395 | 10-01-85 | Brian Evans | 65 | 60.3 | |
| | AB | 5,770,722 | 06-23-98 | David J. Lockhart et al. | 536 | 25.3 | |
| | AC | 5,807,522 | 09-15-98 | Patrick O. Brown et al. | 422 | 50 | |
| | AD | 5,843,789 | 12-01-98 | Hiroshi Nomura et al. | 436 | 164 | |
| <i>my</i> | AE | 5,959,098 | 09-99 | Goldberg et al. | 536 | 25.3 | |
| | AF | 6,004,752 | 12-21-99 | Zvi G. Loewy et al. | 435 | 6 | |
| | AG | | | | | | |
| | AH | | | | | | |
| | AI | | | | | | |
| | AJ | | | | | | |
| | AK | | | | | | |

| FOREIGN PATENT DOCUMENTS | | | | | | | |
|--------------------------|----|-----------------|------|---------|-------|-----------|--------------------|
| | | Document Number | Date | Country | Class | Sub-Class | Translation Yes No |
| | AL | | | | | | |
| | AM | | | | | | |
| | AN | | | | | | |
| | AO | | | | | | |
| | AP | | | | | | |
| | AQ | | | | | | |

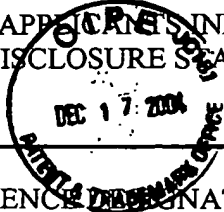
| OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.) | | |
|--|----|---|
| <i>my</i> | AR | M. Glazer et al., "High Surface Area Substrates for DNA Arrays", Mat. Res. Soc. Symp. Proc. Vol. 576, 1999 Materials Research Society, pgs. 371-375 |
| <i>my</i> | AS | Thomas H. Elmer, "Porous and Reconstructed Glasses", Engineered Materials Handbook, Vol. 4, The Materials Information Society, pgs. 427-432 |
| <i>my</i> | AT | M. Glazer et al., "Colloidal Silica Films For High-Capacity DNA Probe Arrays", Chem. Mater. 2001, Vol. 13, pgs. 4773-4782 |
| | AU | |
| | AV | |
| | AW | |

EXAMINER: *Melanne* DATE CONSIDERED: *1/12/05*

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

SP03-091

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| FORM PTO-1449 (MODIFIED) | ATTORNEY DOCKET NO. SP03-091 | SERIAL NO. 10/629,444 |
| LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT | APPLICANT Paul S. Danielson, et al. | |
| | FILING DATE TBA | GROUP: 1645 |



| REFERENCE DESIGNATION | | | | U.S. PATENT DOCUMENTS | | | |
|-----------------------|----|-----------------|----------|-----------------------|-------|-----------|------------------------|
| Examiner Initial | | Document Number | Date | Name | Class | Sub-Class | Filing Date if Approp. |
| <i>my</i> | AA | 2003/0036062 | 02-20-03 | Yijia Bao et al. | 435 | 6 | |
| <i>my</i> | AB | 2003/0003474 | 01-02-03 | C.W. Tanner et al. | 435 | 6 | |
| | AC | | | | | | |
| | AD | | | | | | |
| | AE | | | | | | |
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| FOREIGN PATENT DOCUMENTS | | | | | | | |
|--------------------------|----|-----------------|----------|---------|-------|-----------|--------------------|
| | | Document Number | Date | Country | Class | Sub-Class | Translation Yes No |
| <i>my</i> | AL | WO 00/33078 | 06-08-00 | PCT | | | X |
| | AM | | | | | | |
| | AN | | | | | | |
| | AO | | | | | | |
| | AP | | | | | | |
| | AQ | | | | | | |

| OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.) | |
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EXAMINER: *Melanie* DATE CONSIDERED: *1/12/05*

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